

Flip Chip Bonder AFM-15 Ultrasonic Gold-to-Gold Interconnect



Key Features

- **For High Precision Cost-Sensitive Applications**
All in one process for mounting and bonding
- **High Speed and Accuracy Mounting**
Speed: 0.8 sec/IC Chip Component
Accuracy: +/- 8µm
- **Small Footprint:** 1.7 Square Meters
- Easy Operation with Color Touch Screen
- Inspection of Known Good Die from wafer
- Capable to handle FR4, Ceramic or Silicon

No Clean
No Lead Process

Specifications

	AFM-15	AFM-22	MDM-20
Bonding Process	Gold-to-gold interconnection (ultra sonic)	Heat compression (NCP, ACP, NCF, ACF, C4 and etc)	Glue dispensing
Products	TCXO, SAW, OPTO, High Frequency and etc	Module, OPTO and etc	All of left products
IC	MAX: 5.0W x 5.0D x 1.0T mm MIN: 0.3W x 0.3D x 0.1T mm	MAX: 30W x 30D x 0.635T mm MIN: 3W x 3D x 0.25T mm	- -
Board	MAX: 180W x 120D x 3.2T mm MIN: 50W x 50D x 0.3T mm	MAX: 180W x 120D x 1.6T mm MIN: 50W x 50D x 0.4T mm	MAX: 200W x 150D x 2.0T mm MIN: 30W x 30D x 0.3T mm
Cycle Time	0.8sec/IC (excluding bonding process time)	5.0sec/IC (excluding bonding process time)	-
Accuracy	±8µm/3σ	±3µm/3σ	±10µm (nozzle positioning accuracy)
MAX Load	20N (special 100N)	372.4N	-
IC Supply	5/6 inch wafer (8 inch option)	2inch tray and etc	-
Machine size	1,200W x 1,450D x 1,550H mm	750W x 910D x 1,760H mm	740W x 1,140D x 1,550H mm
Machine weight	2,000kg	1,100kg	680 kg
Standard Features	Pre/Mounting heater table Nozzle auto cleaning & monitoring US checking IC height measurement Bump detection Wafer expand Wafer θ axis correction Hot blow Production management data	Mounting heater table Hepa-filter Parallelism verification Bonding position verification Temperature calibration Production management data	Various dispensing features Nozzle auto cleaning Pre/Dispense heater table Height detection Production management data
Option and Special Features	Magazine Loader/Unloader Ionizer Carrier handling Hepa-filter Plasma cleaning unit Load/US sampling Nozzle surface monitoring 8 inch wafer Map data High accuracy mode	Magazine Loader/Unloader Ionizer 3.4inch tray 6inch wafer Low pressure capability (min: 10g)	Magazine Loader/Unloader Post heater table Carrier handling Dispensing monitoring Sylinge temperature adjustment